

COMPAL CONFIDENTIAL

MODEL NAME : ADM60

PCB NO : DAA000AD000

BOM P/N : 4319XY31L01/L02

Park City 12" UMA

Skylake U

2015-09-25

REV : 1.0 (A00)

@ : Nopop Component

EMC@ : EMI, ESD and RF Component
@EMC@ : EMI, ESD and RF Nopop Component
CXDP@ : XDP Component
CONN@ : Connector Component
X76@ : SATA REDRIVER OPTION

MB PCB

Part Number	Description
DAA000AD000	PCB 12K LA-C621P REV0 MB

Layout Dell logo



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REV: A00
PWB: 6N3K7

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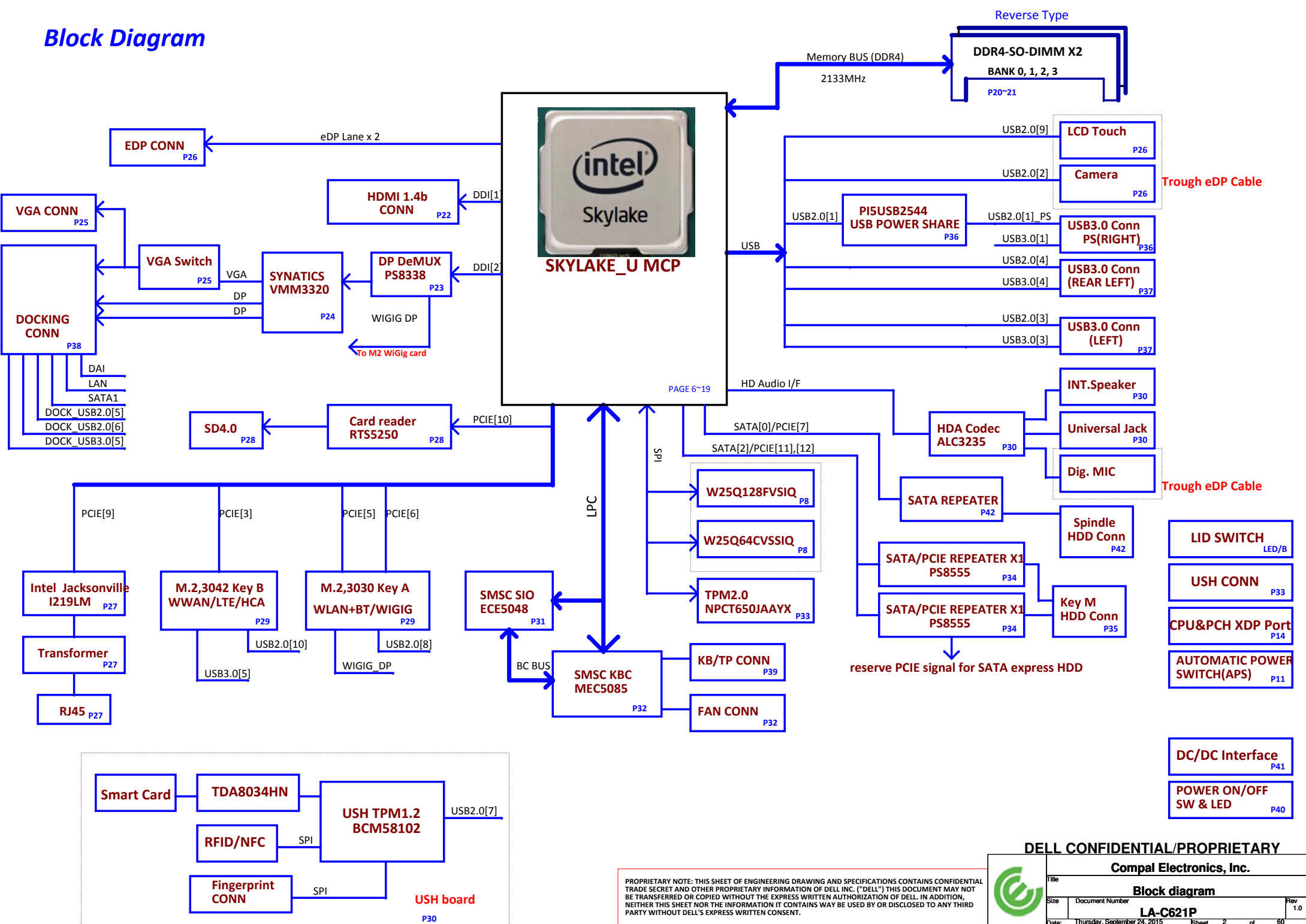


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Block Diagram



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POWER STATES

Signal State	SLP S3#	SLP S4#	SLP S5#	SLP A#	ALWAYS PLANE	M PLANE	SUS PLANE	RUN PLANE	CLOCKS
S0 (Full ON) / M0	HIGH	HIGH	HIGH	HIGH	ON	ON	ON	ON	ON
S3 (Suspend to RAM) / M3	LOW	HIGH	HIGH	HIGH	ON	ON	ON	OFF	OFF
S4 (Suspend to DISK) / M3	LOW	LOW	HIGH	HIGH	ON	ON	OFF	OFF	OFF
S5 (SOFT OFF) / M3	LOW	LOW	LOW	HIGH	ON	ON	OFF	OFF	OFF
S3 (Suspend to RAM) / M-OFF	LOW	HIGH	HIGH	LOW	ON	OFF	ON	OFF	OFF
S4 (Suspend to DISK) / M-OFF	LOW	LOW	HIGH	LOW	ON	OFF	OFF	OFF	OFF
S5 (SOFT OFF) / M-OFF	LOW	LOW	LOW	LOW	ON	OFF	OFF	OFF	OFF

PM TABLE

State	power plane	+5V_ALW +3.3V_ALW +3.3V_ALW_DSW +3.3V_ALW_PCH +RTC_CELL +1.8V_PRIM +1.0V_PRIM +1.0V_PRIM_CORE +5V_ALW2 +3.3V_ALW2 +3.3V_RTC_LDO +1.0V_MPHYGT	+3.3V_SUS +1.2V_MEM +1.0V_VCCST +2.5V_MEM	+5V_RUN +3.3V_RUN +0.6V_DDR_VTT +1.5V_RUN	+3.3V_M	(M-OFF) +3.3V_M +VCC_CORE +VCC_GT +1.0VS_VCCIO +VCC_SA
S0	ON	ON	ON	ON	ON	ON
S3	ON	ON	OFF	ON	OFF	OFF
S5 S4/AC	ON	OFF	OFF	ON	OFF	OFF
S5 S4/AC doesn't exist	OFF	OFF	OFF	OFF	OFF	OFF

Layer No.	Name	Er	Material	Thickness (Material SPEC.) Unit : mil	Thickness (Actuality) Unit : mil
			SolderMask	TU662	0.5
			Add Plating		
1	Top		Copper foil	0.5oz+plating	1.8
		3.7	Prepreg	1080	1.6
2	GND		Copper foil	1oz	1.25
		3.7	Core	4mil	3.87
3	IN 1		Copper foil	1oz	1.25
		3.8	Prepreg	2116H	1.3
4	GND/PWR		Copper foil	1oz	1.25
		3.7	Core	4mil	3.87
5	IN 2		Copper foil	1oz	1.25
		3.8	Prepreg	1080H x2	1.4
6	IN 3		Copper foil	1oz	1.25
		3.7	Core	4mil	3.87
7	GND/PWR		Copper foil	1oz	1.25
		3.8	Prepreg	2116H	1.3
8	IN 4		Copper foil	1oz	1.25
		3.7	Core	4mil	3.87
9	GND		Copper foil	1oz	1.25
		3.7	Prepreg	1080	1.6
10	Bottom		Copper foil	0.5oz+plating	1.8
			Add Plating		
			SolderMask	TU662	0.5
Overall Thickness (1.2mm ± 10%)					48.28000
					1.226312

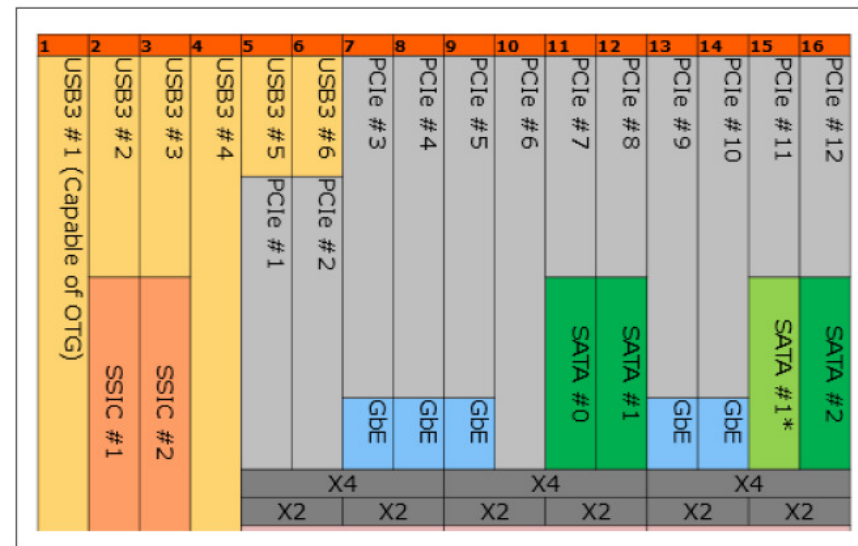
USB3.0	SSIC	PCIE	SATA	DESTINATION
USB3.0-1				JUSB3-->Right
USB3.0-2	SSIC-1			EDOCK PORT1
USB3.0-3	SSIC-2			JUSB1-->LEFT
USB3.0-4				JUSB2-->Rear LEFT
USB3.0-5		PCIE-1		M2 3042(WWAN)
USB3.0-6		PCIE-2		NA
		PCIE-3		M.2 3042(HCA or QCA LTE)
		PCIE-4		NA
		PCIE-5		M.2 3030(WLAN)
		PCIE-6		M.2 3030(WIGIG)
		PCIE-7	SATA-0	HDD SATA
		PCIE-8	SATA-1	EDOCK E-SATA
		PCIE-9		LOM
		PCIE-10		Card Reader
		PCIE-11	SATA-1*	M.2 Socket 3 (Key M) (PClex2 or SATA)
		PCIE-12	SATA-2	

USB PORT#	DESTINATION
1	JUSB1-->Right
2	Camera
3	JUSB2-->LEFT
4	JUSB3-->Rear LEFT
5	EDOCK PORT1
6	EDOCK PORT2
7	USH
8	M.2 304230(BT)
9	Touch Screen
10	M2 3042(WWAN)

USH	0	BIO
	1	NA

Check

High Speed I/O (HSIO) Lane Multiplexing in SKL U

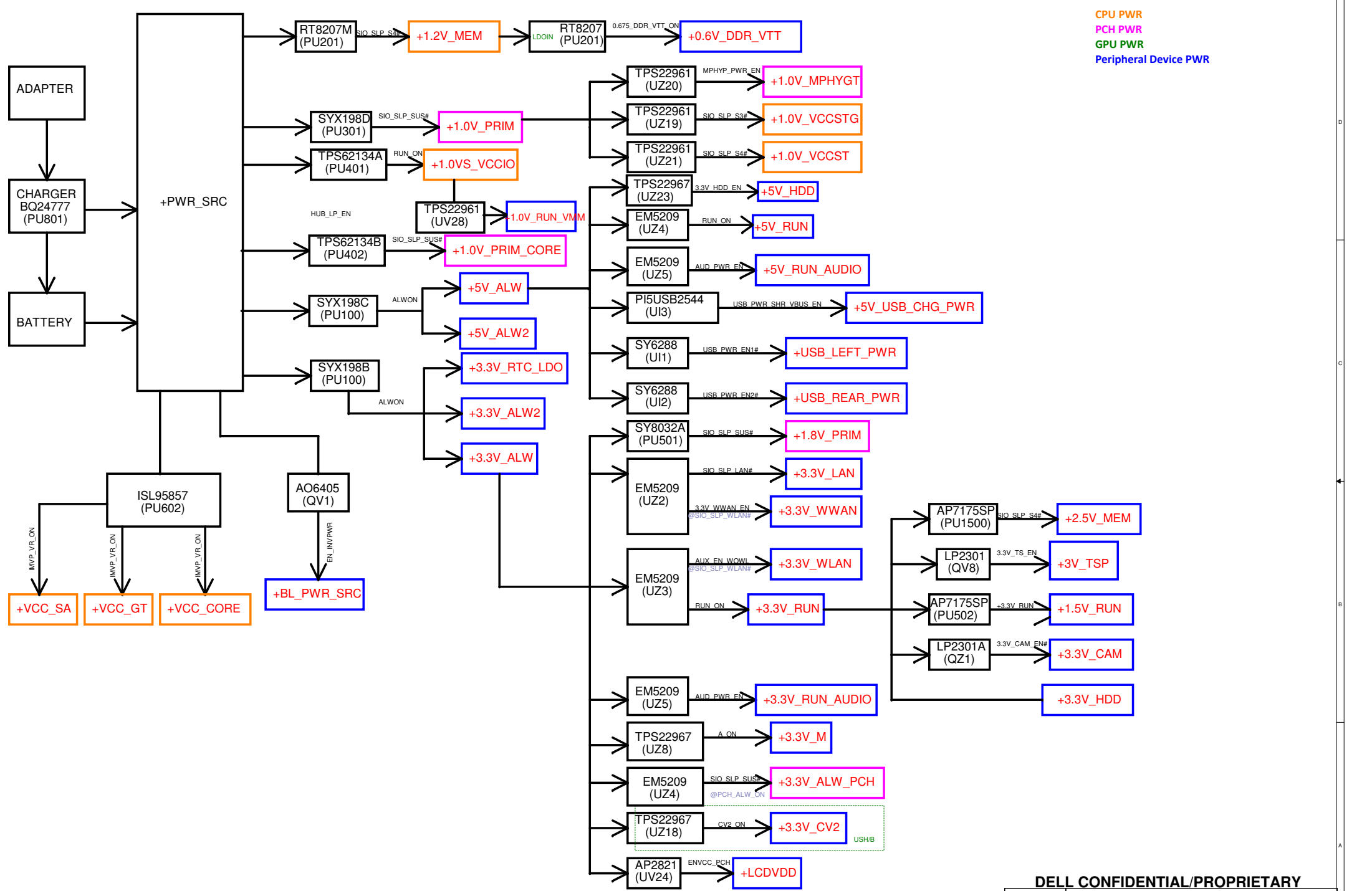


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Port assignment		
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CPU PWR
PCH PWR
GPU PWR
Peripheral Device PWR

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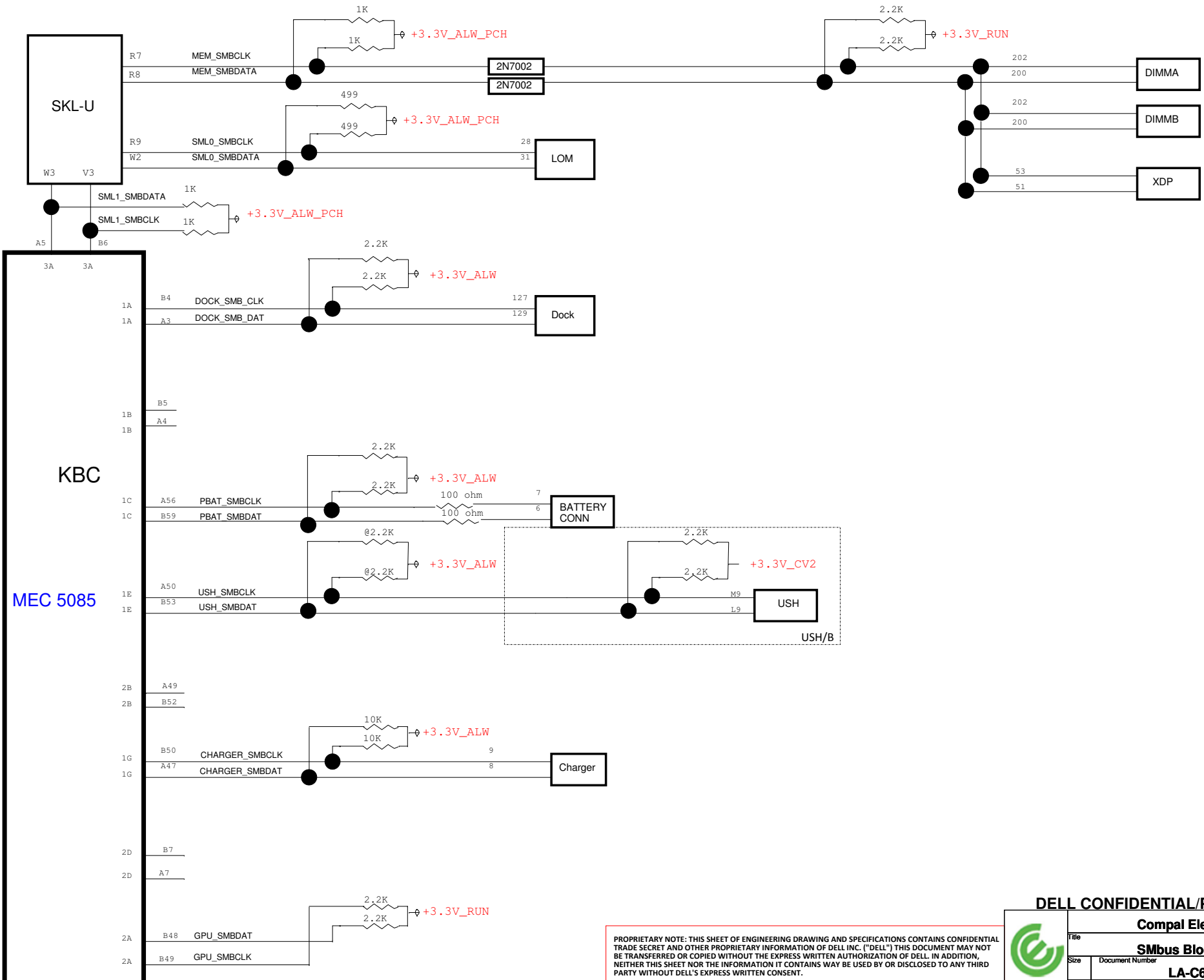
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Power rails

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Title: **SMBus Block diagram**

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